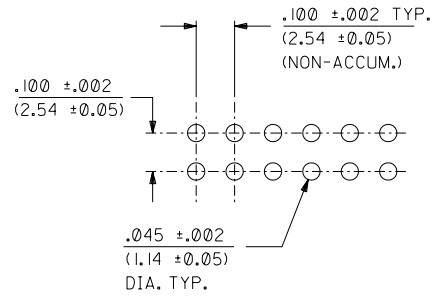
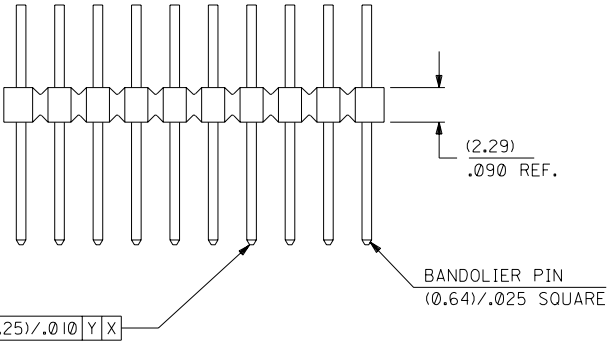
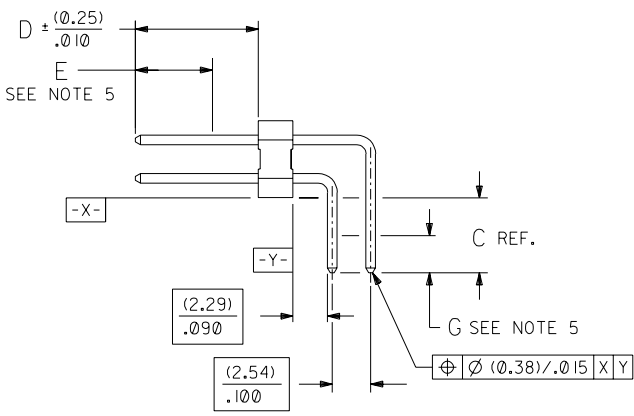
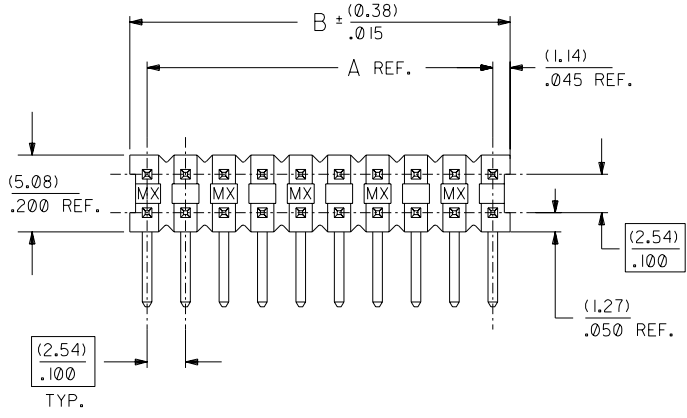


CKT. SIZE	DIM. A REF.		DIM. B REF.	
	(MM)	INCH	(MM)	INCH
4	(2.54)	.100	(4.83)	.190
6	(5.08)	.200	(7.37)	.290
8	(7.62)	.300	(9.91)	.390
10	(10.16)	.400	(12.45)	.490
12	(12.70)	.500	(14.99)	.590
14	(15.24)	.600	(17.53)	.690
16	(17.78)	.700	(20.07)	.790
18	(20.32)	.800	(22.61)	.890
20	(22.86)	.900	(25.15)	.990
22	(25.40)	1.000	(27.69)	1.090
24	(27.94)	1.100	(30.23)	1.190
26	(30.48)	1.200	(32.77)	1.290
28	(33.02)	1.300	(35.31)	1.390
30	(35.56)	1.400	(37.85)	1.490
32	(38.10)	1.500	(40.39)	1.590
34	(40.64)	1.600	(42.93)	1.690
36	(43.18)	1.700	(45.47)	1.790
38	(45.72)	1.800	(48.01)	1.890
40	(48.26)	1.900	(50.55)	1.990
42	(50.80)	2.000	(53.09)	2.090
44	(53.34)	2.100	(55.63)	2.190
46	(55.88)	2.200	(58.17)	2.290
48	(58.42)	2.300	(60.71)	2.390
50	(60.96)	2.400	(63.25)	2.490
52	(63.50)	2.500	(65.79)	2.590
54	(66.04)	2.600	(68.33)	2.690
56	(68.58)	2.700	(70.87)	2.790
58	(71.12)	2.800	(73.41)	2.890
60	(73.66)	2.900	(75.95)	2.990
62	(76.20)	3.000	(78.49)	3.090
64	(78.74)	3.100	(81.03)	3.190
66	(81.28)	3.200	(83.57)	3.290
68	(83.82)	3.300	(86.11)	3.390
70	(86.36)	3.400	(88.65)	3.490
72	(88.90)	3.500	(91.19)	3.590
74	(91.44)	3.600	(93.73)	3.690
76	(93.98)	3.700	(96.27)	3.790
78	(96.52)	3.800	(98.81)	3.890
80	(99.06)	3.900	(101.35)	3.990



RECOMMENDED P.C. BOARD HOLE LAYOUT



NOTES:

- PIN PUSHOUT FORCE: 4 LBS. MINIMUM
- FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
- PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE. (APPROX. .025 LNG X .006 WD. REF.) - 2 LOCATIONS
- WAFER TO BE FLAT WITHIN (0.03 MM/CM)/.003 IN./IN.
- MEASURE POINT FOR PLATING THICKNESS.
- THIS PRODUCT CONFORMS TO MOLEX PRODUCT SPEC. PS-70203.
- FOR ASSEMBLIES WITH VOIDS, REFER TO DRAWING NUMBER SDA-70203-5001-9999.
- PACKAGING INFORMATION: (UNLESS OTHERWISE NOTED IN TABLES)
CIRCUIT SIZE PACKAGING DRAWING
4 THROUGH 8 PK-70873-0353
10 AND OVER PK-70873-0075

FINISH:

- TIN - .000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
 - 15 GOLD - .000015 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - 30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
- *THE PRIMARY SHIPPING CARTON WILL BE LABELED *COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

MATERIAL:

WAFER - G.F. POLYESTER; 94V-0; COLOR: BLACK
PIN - PHOSPHOR BRONZE

D	LEAD FREE
	UCP2004-1770
	RWHITE 04/04/23
CI	REVISE PKGNG
	ECN UDT2000-0949
	SCHAFER 00/4/6
C	REVISED
	PER ECN # U60711
	1/8/96 BJS/RCB
BI	ADDED EDP
	PER ECN # U60256
	95/08/23 CAC
B	VOIDED EDP NO'S
	PER ECN # U60097
	95/07/27 CAC
2	D
1	D
A	RELEASED
	PER ECN # U31656
	11/18/93 REED

DIMENSIONS SHOWN (METRIC) INCH		UNLESS OTHERWISE SPECIFIED TOLERANCES ANGULAR ± 1/2°	
		INCH METRIC	
3 PLACE	± .005	---	---
2 PLACE	± .01	± 0.13	---
1 PLACE	---	± 0.25	---
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY: SMR	CHK'D. BY: SMR	FILE NAME: S70203X1	SHEET NO. DATE: 1 OF 2 11/18/93
APPR. BY: SCALE: 4:1		SEE CHART SDA-70203-0001-5000	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION. DA C			

Engineering drawing header with columns for part number, release, dimensions (C, D), plating, connector end plating, P.C. board end plating, and FOR PKG. INFO. SEE NOTE 8, SHEET 1.

Table of CKTS, EDP NUMBER, and ENG NUMBER for various components, listing part numbers and quantities.

Technical notes, revision table (LTR., REVISIONS), dimensions (INCH/METRIC), and title block information including MOLEX INCORPORATED logo and drawing title 'SALES ASSY-DUAL ROW WAFER W/BREAK-OFF OPTION RIGHT ANGLE/.025 SQ PINS'.